1 V3.1 (04-Jan-2022)

- Updated logo, disclaimer, copyright.

2 V3.0 (04-Nov-2016)

- Product status changed to Production, datasheet status changed to Final.
- Notes added that DC-DC converter Boost mode is not supported, in section 5 (p.16) and section 7 (p.137).

3 V2.0 (25-Aug-2016)

- Product status changed to Qualification, datasheet status changed to Preliminary.
- DA14583 qualified to Bluetooth Specification 4.2. Datasheet title and document content changed accordingly.
- Bluetooth Smart changed to Bluetooth low energy as per Bluetooth SIG directive.
- Table 3 (Pin Description), p.5/6:
  - Added note that the SPI pins of Port P2 shall not be remapped or used for any other purpose, because they are used for accessing the internal Flash memory during booting.
- Section 3.3 (Memories), p.9:
  - Added text on Advanced Bootloader to OTP description.
- Section 3.6.7 (Input/Output Ports), p.11:
  - Note text updated: SPI pins cannot be remapped or used for any other purpose.
- Section 3.7.2 (Wake-Up Timer), p.12:
  - Added minimum pulse width of 2 sleep clock cycles for wake-up via GPIO.
- Table 126 (SPI_CTRL_REG), p.92: Definition of SPI_MINT corrected:
  - ICU changed to Interrupt Controller.
  - Note on shared interrupts (SPI_INT and AD_INT) removed: not applicable.
- Figure 9 (QFN40 Package Outline Drawing), p.148:
  - Drawing updated to Rev B. Reason: Min/Nom/Max values added for dimensions A, A1, A2, D and E.
- Template updated to new branding guidelines.
- Back page:
  - Definition for datasheet status Final clarified.
  - Disclaimer updated with trademarks statement.
  - RoHS statement updated.
  - Contact information updated.

4 V1.1 (March 6, 2015)

- Order numbers modified (Table1 and Table 2, p.4):
  - DA14583-01AT1 changed to DA14583 - 01F01AT1
  - DA14583-01AT2 changed to DA14583 - 01F01AT2
- Deep Sleep mode removed: not supported. Document updated accordingly in various places.
- Table 3 (Pin Description), p.6: OTP programming voltage on pin VPP corrected to 6.7 V ± 0.1 V.
- Table 276 (Flash memory: DC characteristics), p.141: conditions updated, typical values added.
- Figure 9 (QFN Package Outline Drawing), p.147: drawing updated.

5 V1.0 (February 13, 2015)

- Product status: Development, datasheet status: Target.
- Initial version, derived from DA14580.
- Changes with respect to DA14580:
  - Buck mode DC-DC converter only.
  - Integrated 1 Mbit Flash memory.
  - Package: QFN40.

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